















Figure 1: The proposed optoelectronic architecture based on the concept of a computational cluster, with a high speed optical interconnect. The smart-pixel layer is used as an interface between the computational layer and the interconnect, with the intention of overcoming the problems presented by the bandwidth bottleneck in the links from/to the PCs. The processors in dotted boxes indicate the possibility of using dual processor PCs.

Figure 2: Characterisation of inter-smart-pixel array communication. Communication between a smart-pixel array and the optical interconnect is characterised by B_{SPA} and L_{SPA} . The available bandwidth of the optical interconnect is B_{on} and the optical time-of-flight is L_{OH} . The effective bandwidth and latency in communication between a pair of smart-pixel arrays are $B_{optical}$ and $L_{optical}$ respectively.

Figure 3: Schematic depiction of a BSP computation. Each processor performs a local computation, and this is followed by a communication phase (after combining and re-ordering of data). A barrier synchronisation is then implemented across all the processors.

Figure 4: Implementation of the BSP model on the optoelectronic architecture. A BSP processor consists of a PC and its corresponding smart-pixel array and buffer. Communication between PCs and the smart-pixel layer is allowed during local computation but inter-BSP processor communication is not. Equivalence with two-layered system is indicated.

Figure 5: Schematic of a PC cluster with Myrinet switch.

Figure 6: The communication cost and the ratio of computation cost to communication cost as a function of n , for word size of 16 bits.

Figure 7: The communication cost and the ratio of computation cost to communication cost as a function of n , for word size of 32 bits.